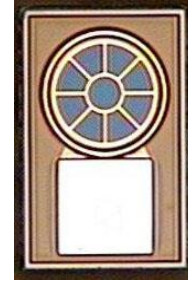


#### Features

- : 850 nm wavelength range
- : Enhanced coupling efficiency
- : Other configurations available on request

#### Description



#### Applications

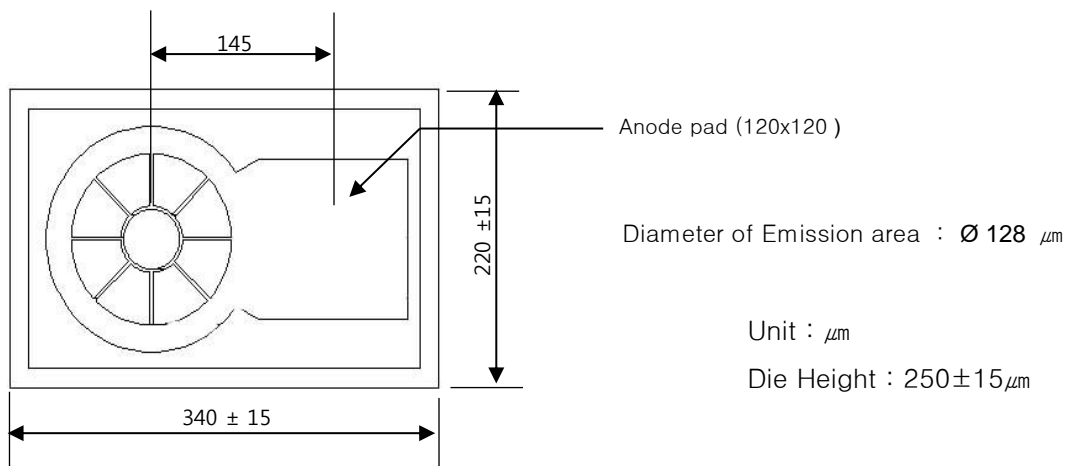
- : Data Link Communication
- : Sensors
- : Industrial applications

#### Absolute Maximum Ratings

Parameter	Rating
Storage Temperature	-40 to 100 °C
Operating Temperature	-20 to 85 °C
Continuous Forward Current	40mA
Pulse Current *	300mA
Continuous Reverse Voltage	5V (@10μA)

\* pulse width : 4μs , duty cycle : 1 ~ 5%

#### Dimensions



### Electro-Optics Characteristics ( $T_a=25^\circ\text{C}$ unless otherwise stated)

Parameters	Symbol	Specified			Unit	Test Conditions
		Min.	Typ.	Max.		
Total Radiant Flux	$\Phi_o$	1.5	2		mW	$I_f=30\text{mA}$
Peak Wavelength	$\lambda_p$	840	850	860	nm	$I_f=30\text{mA}$
Spectral Width	$\Delta\lambda$		20		nm	$I_f=30\text{mA}$ , FWHM
Beam Divergence	$\Theta$		120		Deg.	$I_f=30\text{mA}$ , FWHM
Forward Voltage	$V_f$		1.6		V	$I_f=30\text{mA}$

Test Data were measured in TO header of wire bonded chip

Value is referenced to the vender's measurement system (correlation to customer product is required).

### Thermal Characteristics

Parameters	Symbol	Specified			Unit	Test Conditions
		Min.	Typ.	Max.		
$P_o$ Temp Coefficient	$\Delta P_o / \Delta T$		-0.5		%/°C	$-20^\circ\text{C} \sim 85^\circ\text{C}$ at $I_f=30\text{mA}$
$\lambda_p$ Temp Coefficient	$\Delta\lambda / \Delta T$		0.06		nm/°C	$-20^\circ\text{C} \sim 85^\circ\text{C}$ at $I_f=30\text{mA}$

### Notes

\* These specifications are subject to change without notice.



#### NOTICE

The inherent design of this component causes it to be sensitive to electrostatic discharge(ESD). To prevent ESD-induced damage and/or degradation to equipment, take normal ESD precautions when handling this product